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Vishay Semiconductors

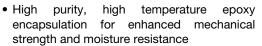
High Performance Schottky Rectifier, 2 x 10 A

Base common cathode cathode Anode VS-20CTQ150SHM3 TO-262AA Base common common cathode common cathode cathode Anode VS-20CTQ150SHM3

PRINMARY CHARACTERISTICS						
Package	D ² PAK (TO-263AB), TO-262AA					
I _{F(AV)}	2 x 10 A					
V_{R}	150 V					
V _F at I _F	0.66 V					
I _{RM} max.	5.0 mA at 125 °C					
T _J max.	175 °C					
E _{AS}	1.0 mJ					
Diode variation	Common cathode					

FEATURES

- 175 °C T_J operation
- Center tap configuration
- Low forward voltage drop
- High frequency operation





COMPLIANT HALOGEN FREE

- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified meets JESD-201 class 1A whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL CHARACTERISTICS VALUES UNITS								
I _{F(AV)}	Rectangular waveform	20	A					
V _{RRM}		150	V					
I _{FSM}	t _p = 5 μs sine	1030	А					
V _F	10 A _{pk} , T _J = 125 °C (per leg)	0.66	V					
T _J	Range	-55 to +175	°C					

VOLTAGE RATINGS							
PARAMETER SYMBOL VS-20CTQ150SHM3 UNITS							
Maximum DC reverse voltage	V_{R}	150	V				
Maximum working peak reverse voltage	V_{RWM}	130	V				

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDI	TEST CONDITIONS		UNITS			
	leg	50 0/ d l - d - d - d - T - d 5 4 00						
See fig. 5 per de	vice I _{F(AV)}	50 % duty cycle at T _C = 154 °C	20					
Maximum peak one cycle		5 μs sine or 3 μs rect. pulse	Following any rated load condition and with	1030	A			
non-repetitive surge current per leg See fig. 7	IFSM	10 ms sine or 6 ms rect. pulse	rated V _{RRM} applied	180				
Non-repetitive avalanche energy per le	g E _{AS}	$T_J = 25 ^{\circ}\text{C}$, $I_{AS} = 1 \text{A}$, $L = 2 \text{mH}$		1.0	mJ			
Repetitive avalanche current per leg	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _R typical		1	Α			



VS-20CTQ150SHM3, VS-20CTQ150-1HM3

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ELECTRICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			UNITS		
		10 A	T _{.1} = 25 °C	0.80	0.88			
Maximum forward voltage drop per leg See fig. 1	V _{FM} ⁽¹⁾	20 A	1j=25 C	0.90	1.0	V		
	V _{FM} ('')	10 A	T _{.1} = 125 °C	0.63	0.66			
		20 A	1j = 125 C	0.73	0.77			
Maximum reverse leakage current per leg	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	3.0	25	μA		
See fig. 2		T _J = 125 °C	v _R = nated v _R	2.7	5.0	mA		
Typical junction capacitance per leg	C _T	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		-	280	pF		
Typical series inductance per leg	L _S	Measured lead to lead 5 mm from package body			8.0	nΗ		
Maximum voltage rate of change	dV/dt	Rated V _R		-	10 000	V/µs		

Note

 $^{^{(1)}\,}$ Pulse width $<300~\mu s,$ duty cycle <2~%

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to +175	°C		
Maximum thermal resistance,	per leg	В	DC aparation	2.0			
junction to case	per package	R _{thJC} DC operation	1.0	°C/W			
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased (Only for TO-262)	0.50			
Approximate weight				2	g		
Approximate weight				0.07	oz.		
Mounting torque	minimum			6 (5)	kgf · cm		
Mounting torque maximum				12 (10)	(lbf \cdot in)		
			Case style D ² PAK (TO-263AB)	20CTQ	150SH		
Marking device			Case style TO-262	20CTQ150-1H			

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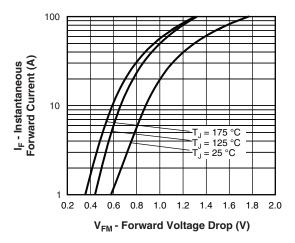


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

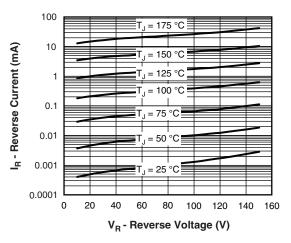


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

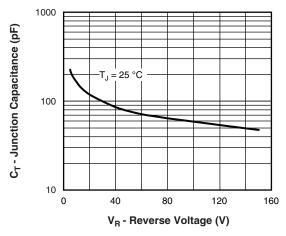


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

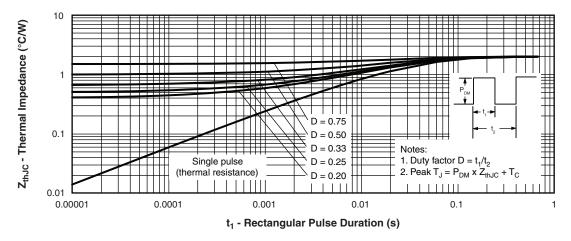


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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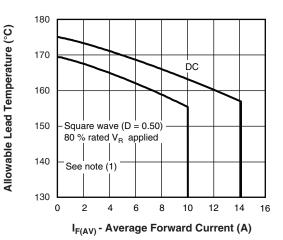


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature

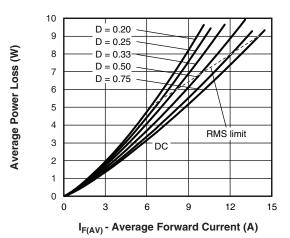


Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

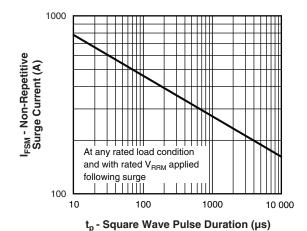


Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

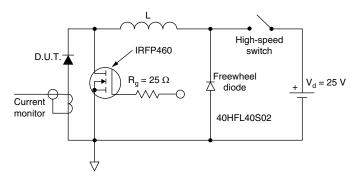


Fig. 8 - Unclamped Inductive Test Circuit

Note

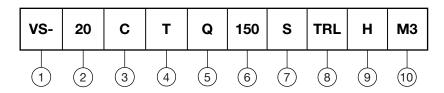
 $\begin{array}{ll} \text{(1)} \;\; \text{Formula used:} \; T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \; \text{at} \; (I_{F(AV)}/D) \; \text{(see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \; \text{(1 - D)}; \; I_R \; \text{at} \; V_{R1} = 80 \; \% \; \text{rated} \; V_R \\ \end{array}$

VS-20CTQ150SHM3, VS-20CTQ150-1HM3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (20 = 20 A)

3 - C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

6 - Voltage rating (150 = 150 V)

7 - • S = D²PAK

• -1 = TO-262

8 - • None = tube

• TRL = tape and reel (left oriented - for D²PAK only)

• TRR = tape and reel (right oriented - for D²PAK only)

9 - H = AEC-Q101 qualified

- M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-20CTQ150SHM3	50	1000	Antistatic plastic tubes				
VS-20CTQ150STRLHM3	800	800	13" diameter reel				
VS-20CTQ150STRRHM3	800	800	13" diameter reel				
VS-20CTQ150-1HM3	50	1000	Antistatic plastic tubes				

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?95046				
Differsions	TO-262AA	www.vishay.com/doc?95419				
Dort marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information		www.vishay.com/doc?95032				



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL		MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

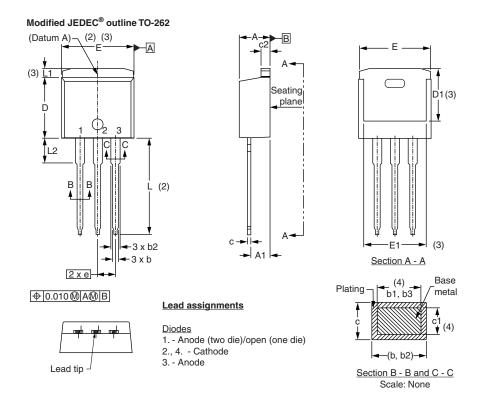
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.10	D BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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